# Results of Operations

## for the Fiscal Year Ending March 31, 2025

C. Uyemura & Co., Ltd.

Standard Market of the Tokyo Stock Exchange（Stock Code：4966）

May 13, 2025

# Overview of Consolidated Financial Results for the Fiscal Year Ended March 31, 2025

[Accounting period]
Japan (1 company): April - March / Overseas (10 companies): January - December

- **Surface finishing materials business**
  - Demand for our mainstay plating chemicals for package PWBs has moderately recovered. The yen's depreciation in the foreign exchange market also contributed to higher sales and segment profit than in the previous fiscal year.

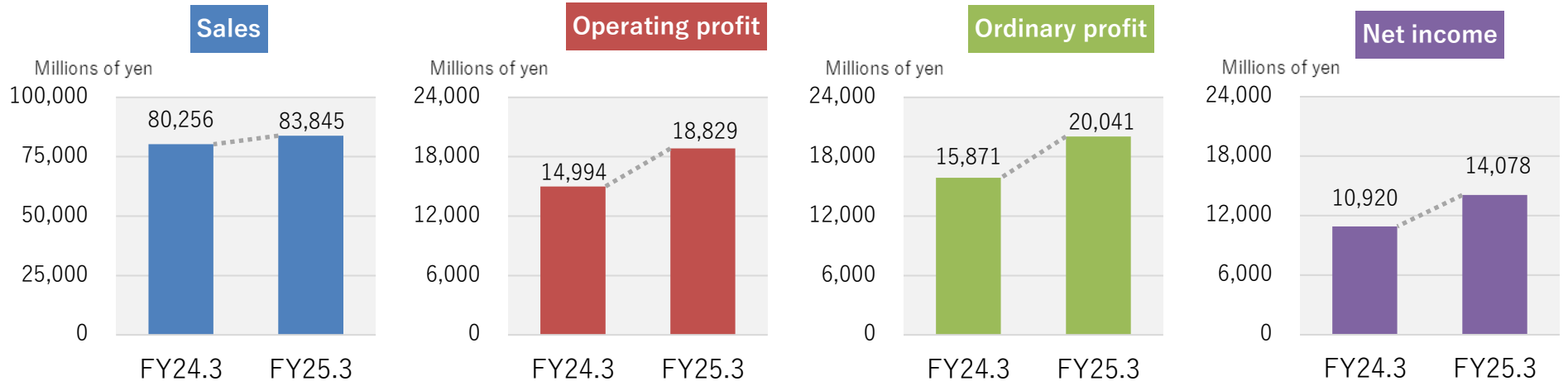
---

- **Surface finishing machinery business**
  - Both segment sales and profit decreased year-over-year as capital investments by package substrate manufacturers came to an end.

---

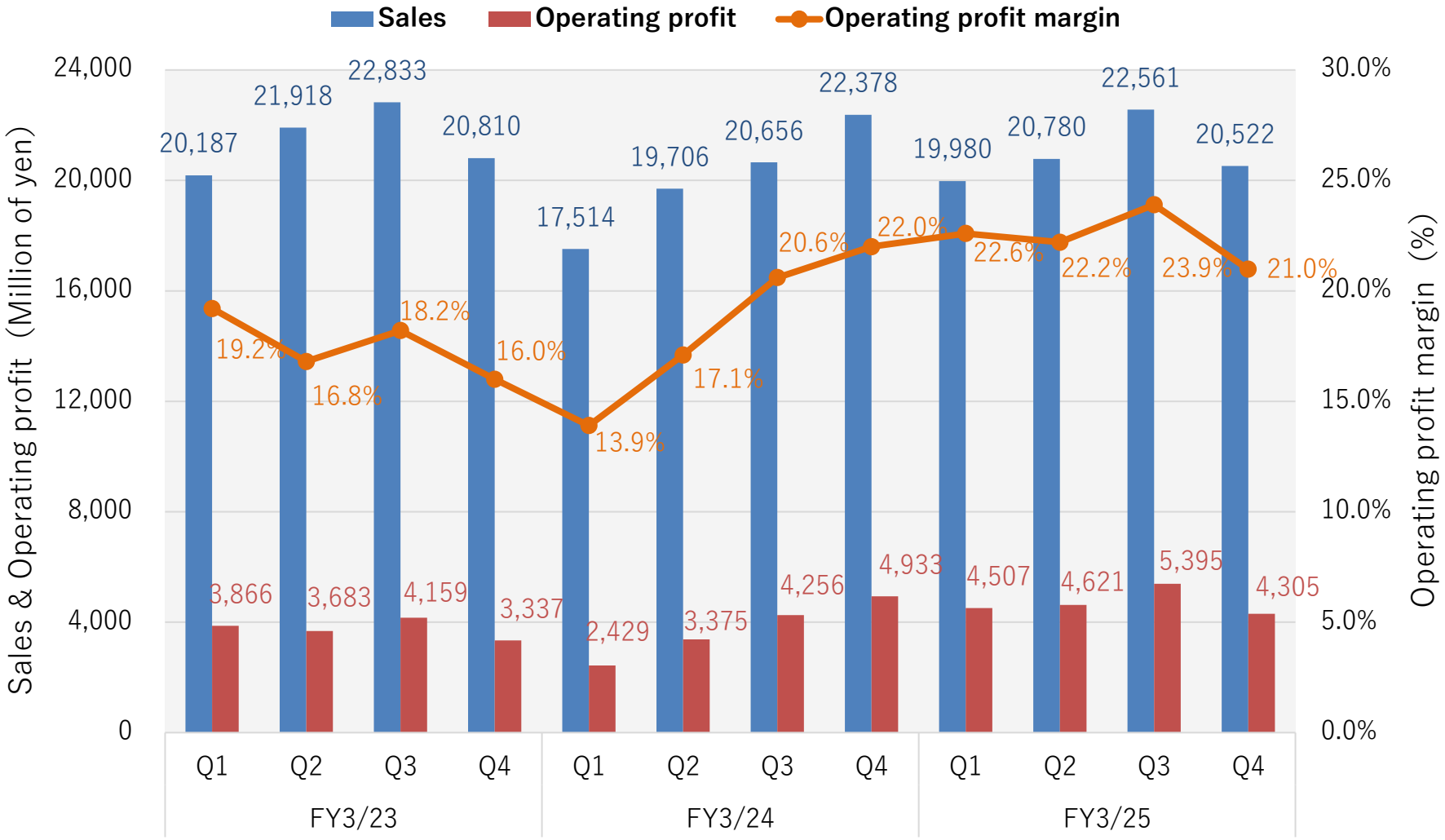
- **Plating job business**
  - Segment loss improved year-over-year. This was due to our efforts to reduce costs and improve yields, despite sluggish demand for plating jobs for automobile parts that led to a decrease in sales year-over-year.

# FY3/25 Financial Results

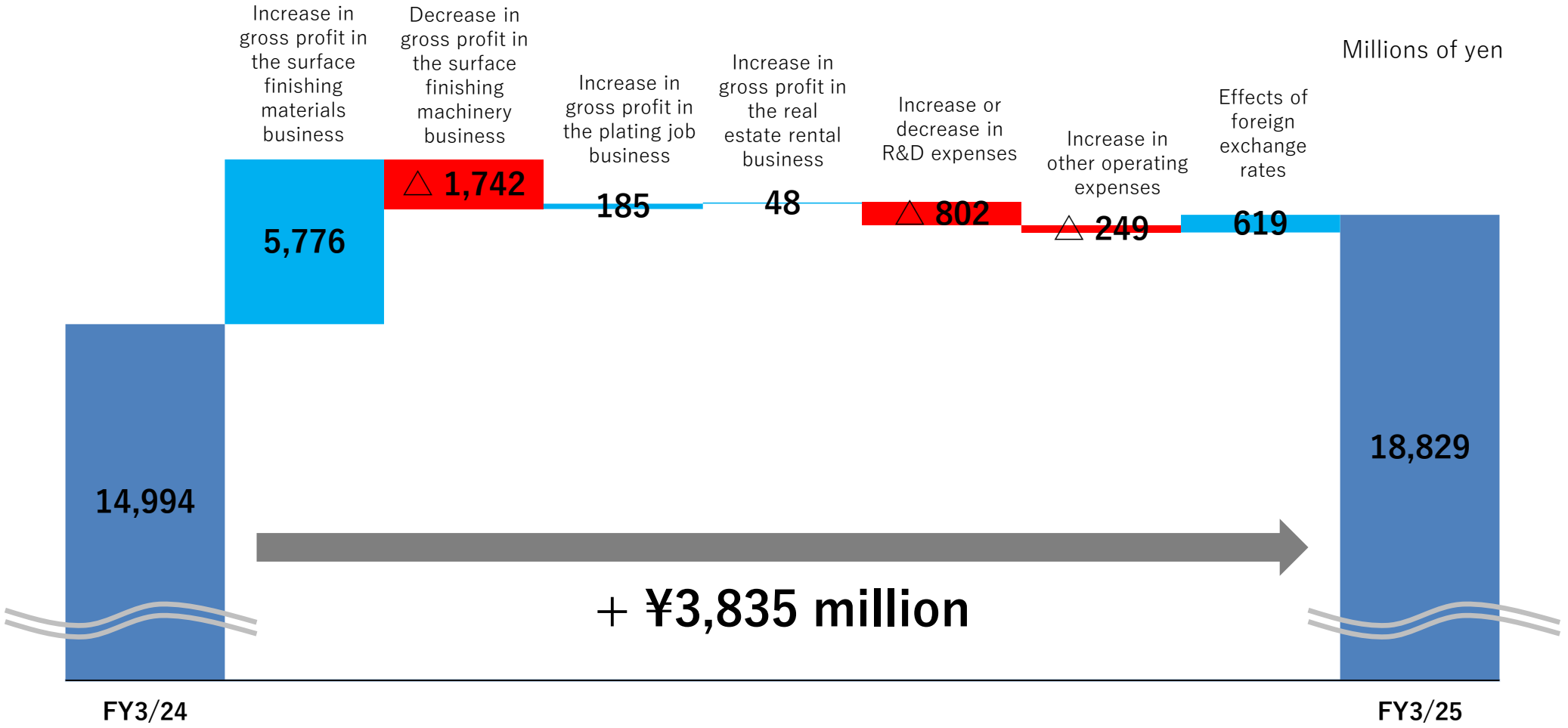



| Millions of yen | FY3/24 Results | FY3/25 Forecast (Revised on Nov.11,2024) | FY3/25 Results | YoY change | Vs. Initial forecast |
|---|---|---|---|---|---|
| Sales | 80,256 | 81,600 | 83,845 | +3,589 (+4.5%) | +2,245 (+2.8%) |
| Operating profit | 14,994 | 18,100 | 18,829 | +3,835 (+25.6%) | +729 (+4.0%) |
| Ordinary profit | 15,871 | 18,800 | 20,041 | +4,170 (+26.3%) | +1,241 (+6.6%) |
| Net income | 10,920 | 12,800 | 14,078 | +3,158 (+28.9%) | +1,278 (+10.0%) |
| Exchange rate: $US | 140.67 yen | 151.41 yen | 151.69 yen | + 11.02 yen | + 0.28 yen |

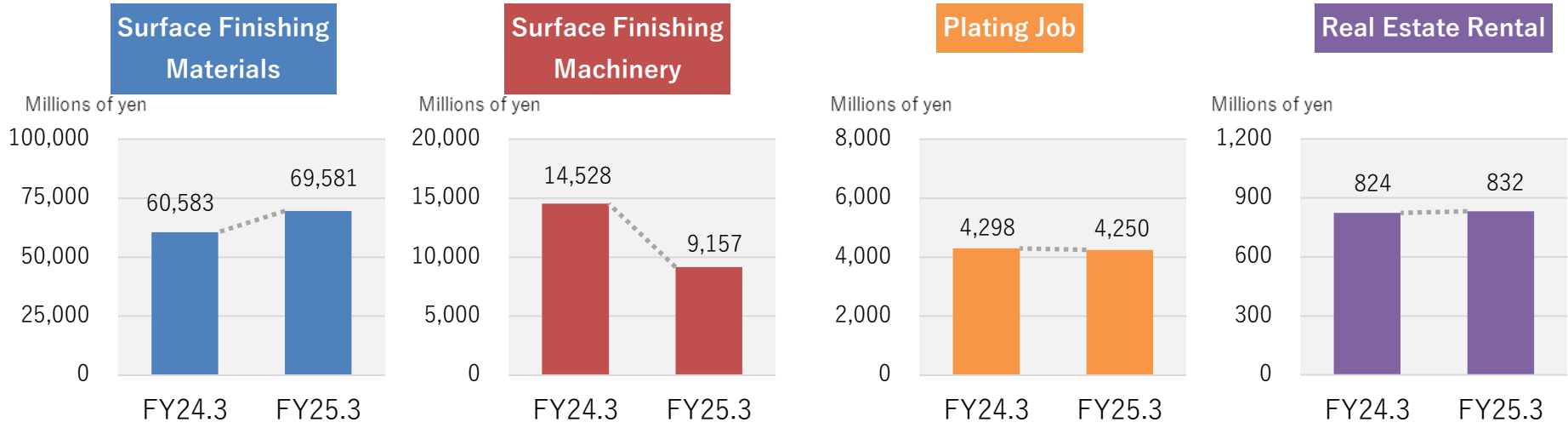
# Quarterly Results



# Changes in Operating profit

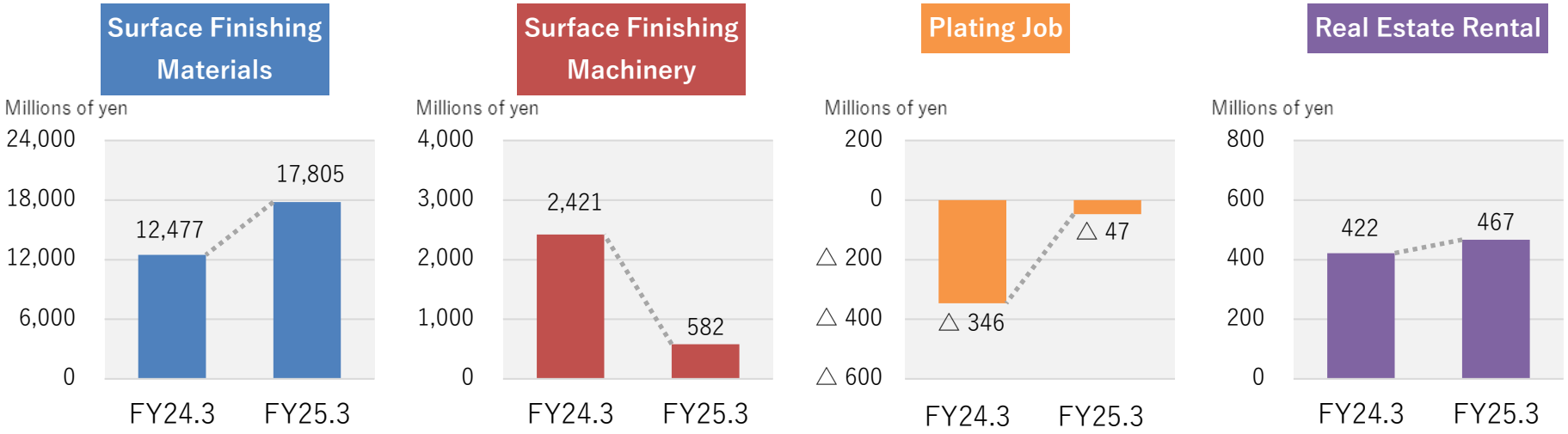


# Sales by Business Segment



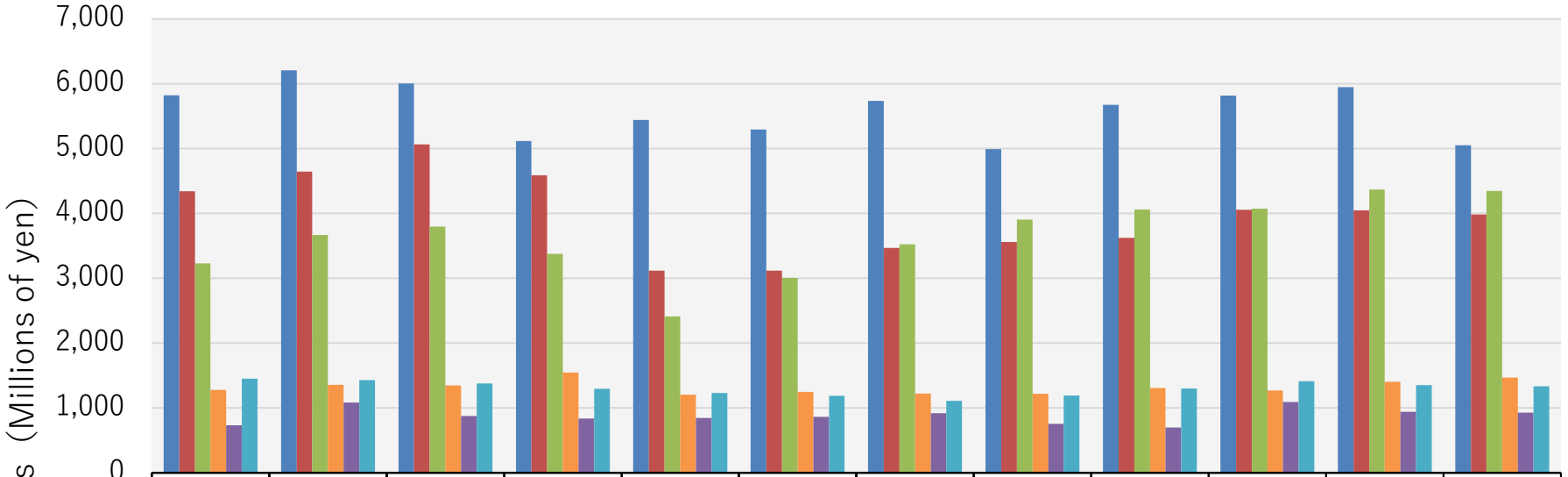

| Millions of yen | FY3/24 Results | FY3/25 Results | Change | Percentage change |
|---|---|---|---|---|
| Surface Finishing Materials | 60,583 | 69,581 | + 8,998 | + 14.9% |
| Surface Finishing Machinery | 14,528 | 9,157 | △ 5,371 | △ 37.0% |
| Plating Job | 4,298 | 4,250 | △ 47 | △ 1.1% |
| Real Estate Rental | 824 | 832 | + 7 | + 0.9% |

# Operating Income by Business Segment



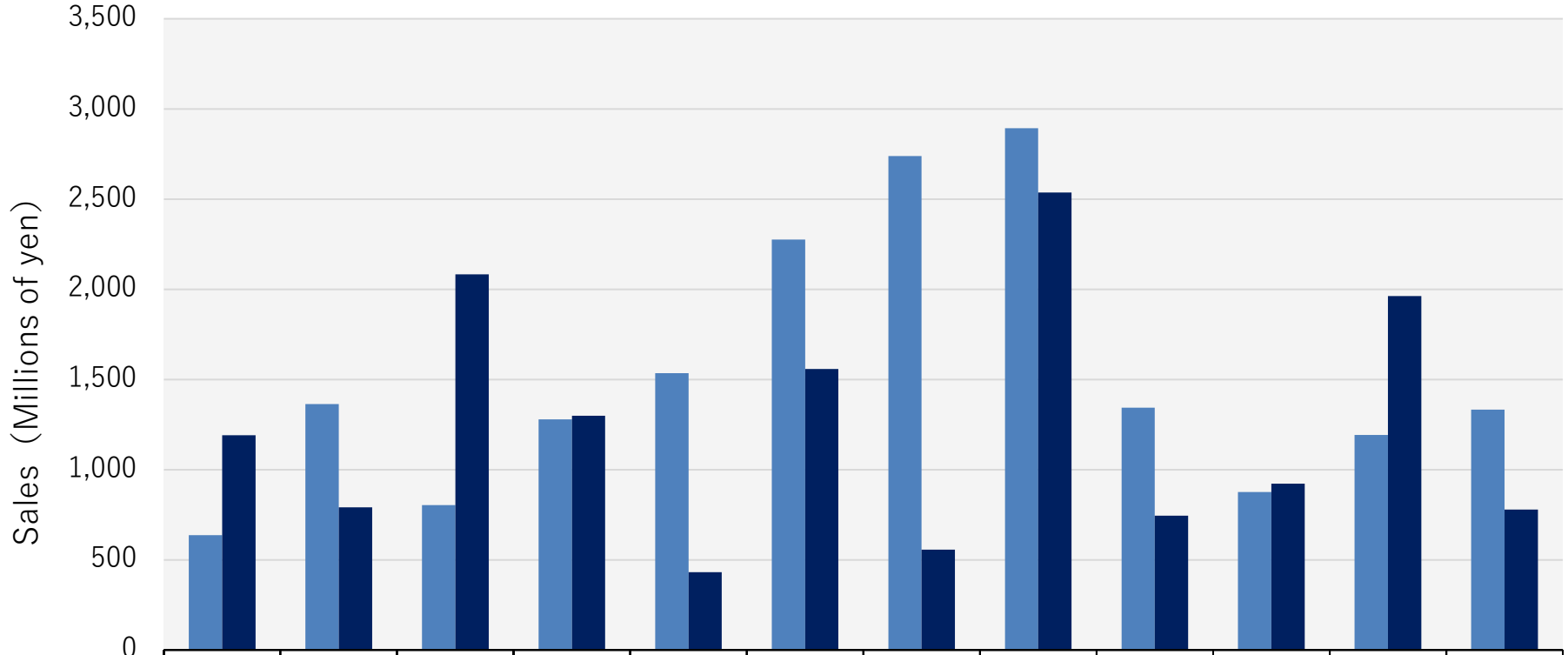

| Millions of yen | FY3/24 Results | FY3/25 Results | Change | Percentage change |
|---|---|---|---|---|
| Surface Finishing Materials | 12,477 | 17,805 | + 5,327 | + 42.7% |
| Surface Finishing Machinery | 2,421 | 582 | △ 1,838 | △ 75.9% |
| Plating Job | △ 346 | △ 47 | + 298 | - |
| Real Estate Rental | 422 | 467 | + 45 | + 10.7% |

# Surface Finishing Materials Business Sales



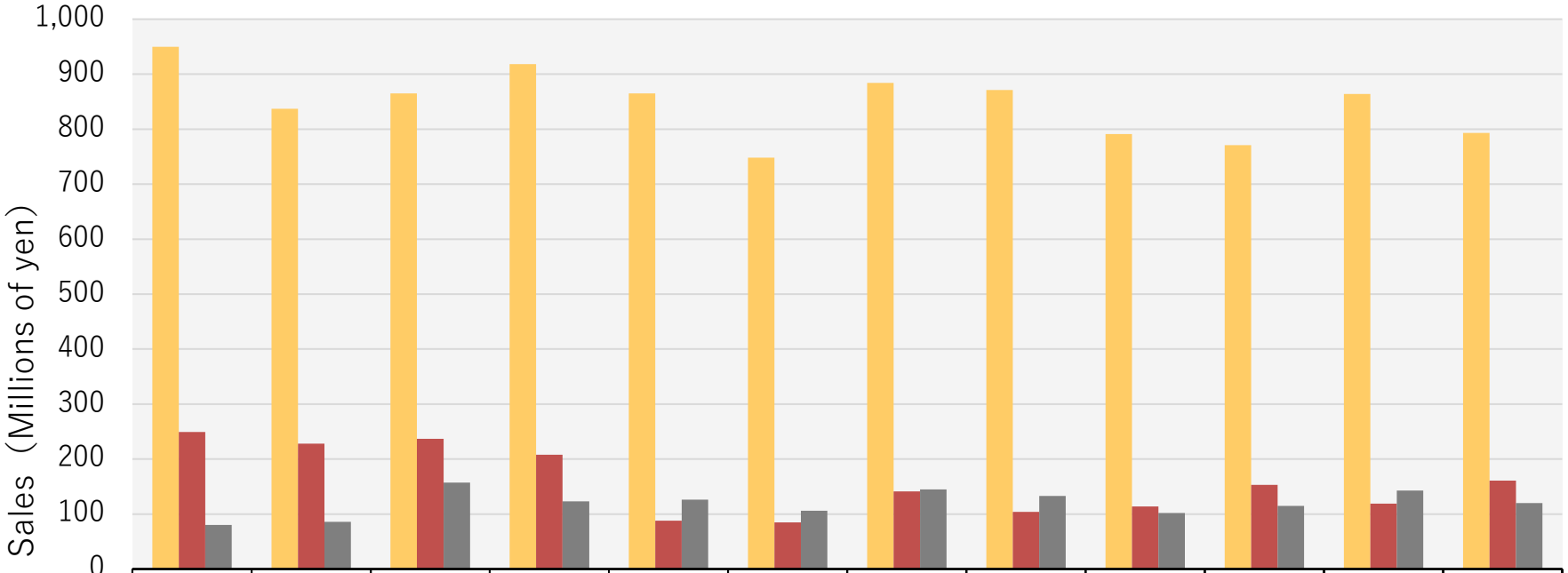

| | Q1 | Q2 | Q3 | Q4 | Q1 | Q2 | Q3 | Q4 | Q1 | Q2 | Q3 | Q4 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | FY3/2023 | | | | FY3/2024 | | | | FY3/2025 | | | |
| Japan | 5,823 | 6,209 | 6,005 | 5,117 | 5,440 | 5,296 | 5,736 | 4,991 | 5,674 | 5,820 | 5,948 | 5,053 |
| Taiwan | 4,341 | 4,644 | 5,065 | 4,591 | 3,117 | 3,118 | 3,467 | 3,558 | 3,626 | 4,058 | 4,049 | 3,985 |
| China | 3,232 | 3,666 | 3,797 | 3,376 | 2,413 | 3,007 | 3,526 | 3,907 | 4,059 | 4,072 | 4,367 | 4,347 |
| Korea | 1,277 | 1,358 | 1,348 | 1,546 | 1,207 | 1,250 | 1,224 | 1,220 | 1,308 | 1,269 | 1,405 | 1,470 |
| ASEAN | 734 | 1,083 | 875 | 838 | 845 | 861 | 919 | 754 | 698 | 1,094 | 941 | 926 |
| US | 1,450 | 1,431 | 1,376 | 1,296 | 1,229 | 1,188 | 1,111 | 1,192 | 1,300 | 1,414 | 1,353 | 1,334 |

# Surface Finishing Machinery Business Sales




| | FY3/2023 | | | | FY3/2024 | | | | FY3/2025 | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | Q1 | Q2 | Q3 | Q4 | Q1 | Q2 | Q3 | Q4 | Q1 | Q2 | Q3 | Q4 |
| Japan | 637 | 1,363 | 804 | 1,278 | 1,535 | 2,276 | 2,739 | 2,893 | 1,344 | 876 | 1,193 | 1,332 |
| Overseas | 1,191 | 791 | 2,083 | 1,298 | 432 | 1,558 | 557 | 2,537 | 745 | 922 | 1,963 | 778 |

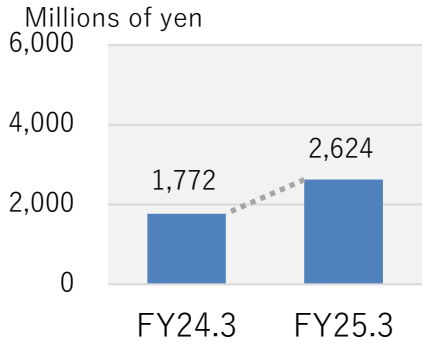
# Plating Job Business Sales



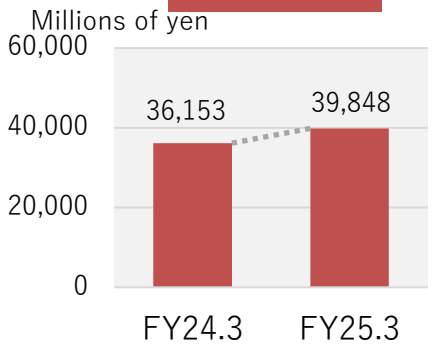

| | FY3/2023 | | | | FY3/2024 | | | | FY3/2025 | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | Q1 | Q2 | Q3 | Q4 | Q1 | Q2 | Q3 | Q4 | Q1 | Q2 | Q3 | Q4 |
| Thailand | 950 | 837 | 865 | 918 | 865 | 748 | 884 | 871 | 791 | 771 | 864 | 793 |
| Taiwan | 249 | 228 | 237 | 208 | 88 | 85 | 141 | 104 | 114 | 153 | 119 | 161 |
| Indonesia | 80 | 86 | 157 | 123 | 126 | 106 | 145 | 133 | 102 | 115 | 143 | 120 |

# Sales by Chemicals Categories

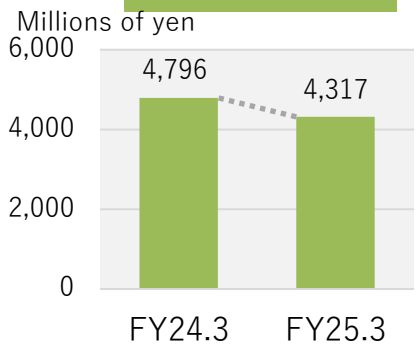
Chemicals for HDD



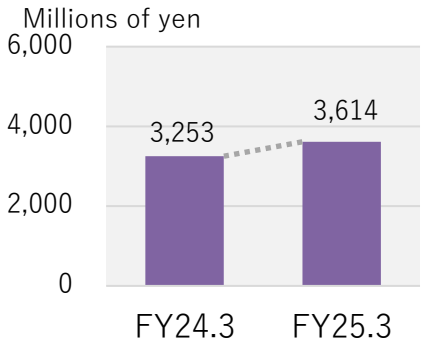

Chemicals for Wafer & PKG




Conventional Electroless Nickel



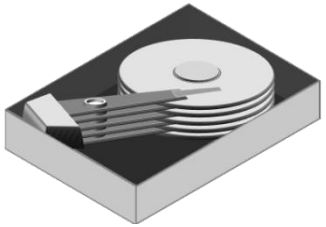
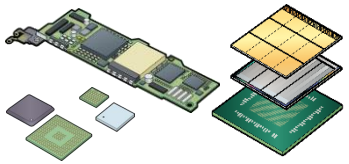
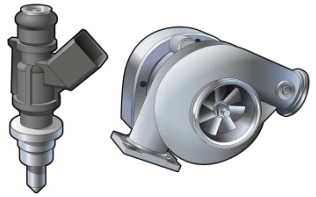
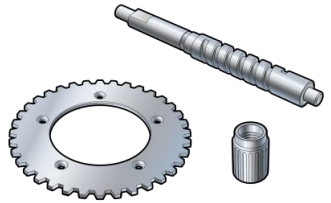

Others




| Millions of yen | FY3/24 Results | % | FY3/25 Results | % | Change | Percentage change |
|---|---|---|---|---|---|---|
| Chemicals for HDD | 1,772 | 3.9% | 2,624 | 5.2% | +852 | +48.1% |
| Chemicals for Wafer & PKG | 36,153 | 78.6% | 39,848 | 79.0% | +3,694 | +10.2% |
| Conventional Electroless Nickel | 4,796 | 10.4% | 4,317 | 8.6% | △ 478 | △ 10.0% |
| Others | 3,253 | 7.1% | 3,614 | 7.2% | +361 | +11.1% |
| Total | 45,975 | 100.0% | 50,405 | 100.0% | +4,429 | +9.6% |

Sales of chemicals are included in the surface finishing materials business. Chemicals do not include abrasive compounds, industrial chemicals, or metals and the like. *Intersegment sales are included.

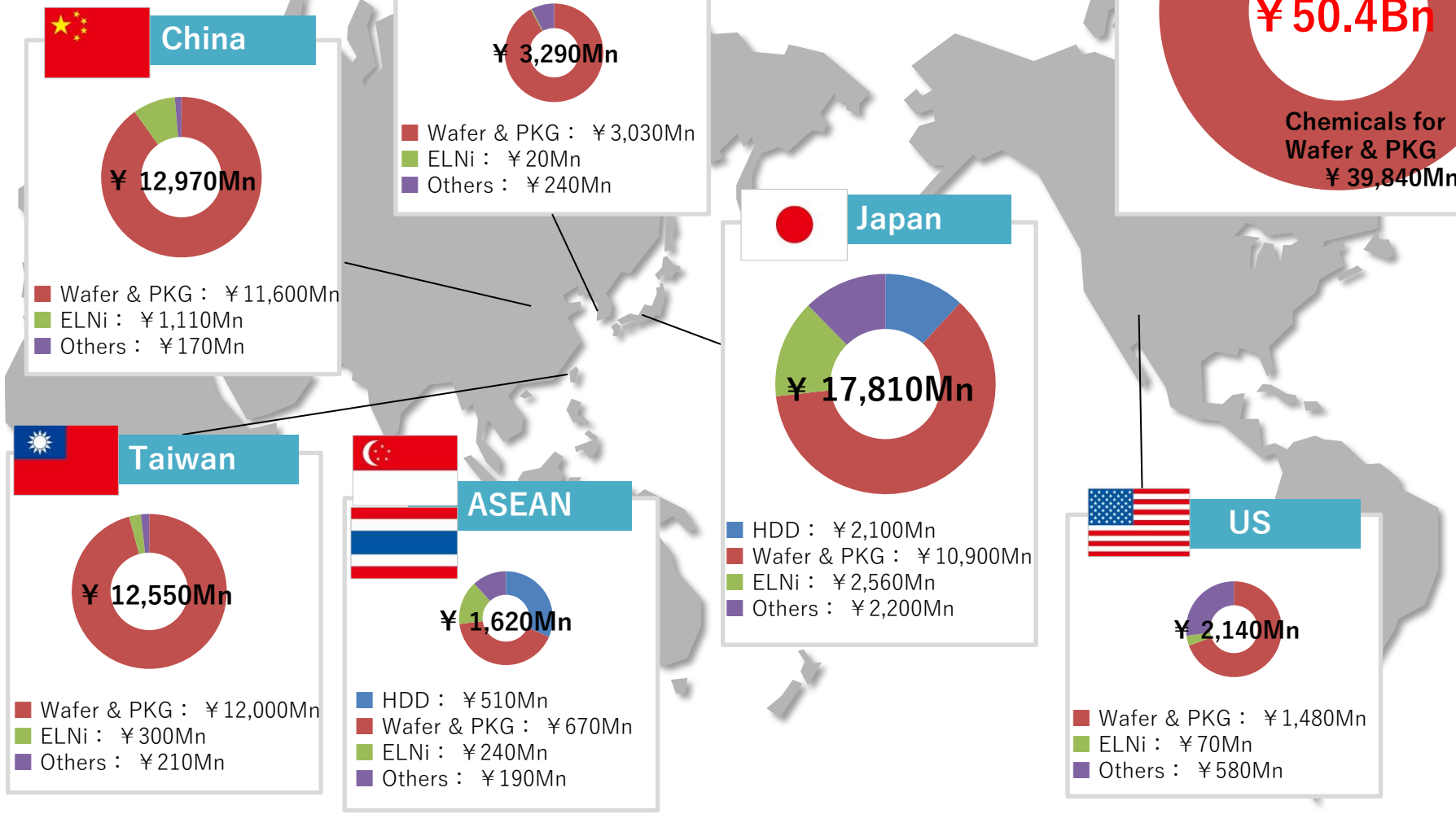
# Chemicals Business – From Uyemura to End Users

| Uyemura's chemicals | Chemicals for HDD | Chemicals for Wafer & PKG | Conventional Electroless Nickel | Others |
|---|---|---|---|---|
| Role | • Electroless nickel (high phosphorus type) ≥ 12 wt% P content NIMUDEN HDX<br>• Non-magnetic properties etc. | • Surface finishing chemicals Electroless nickel/gold plating Electroless nickel/palladium/gold plating, etc.<br>• Electroless copper plating/copper electroplating<br>• High frequency characteristics<br>• Soldering reliability etc. | • Electroless nickel (medium phosphorus type) 8–11 wt% P content NIMUDEN SX, DX, KTY, EL801 (boron type)<br>• Corrosion resistance,<br>• Wear resistance etc. | • Decorative plating (nickel/chrome, zinc plating, plastic plating)<br>• Solder plating<br>• Composite plating chemicals containing PTFE<br>• Decorativeness, corrosion resistance<br>• Wear resistance etc. |
| Intermediate product manufacturers | Aluminum magnetic disk manufacturers  | Package PWBs manufacturers Semiconductor manufacturers  | Various parts manufacturers  | Various parts manufacturers  |
| End products | Hard disks (Servers, PCs, etc.)  | Products that use semiconductors and electronic components  | Automobiles, OA equipment, etc.  | Automobiles and others  |

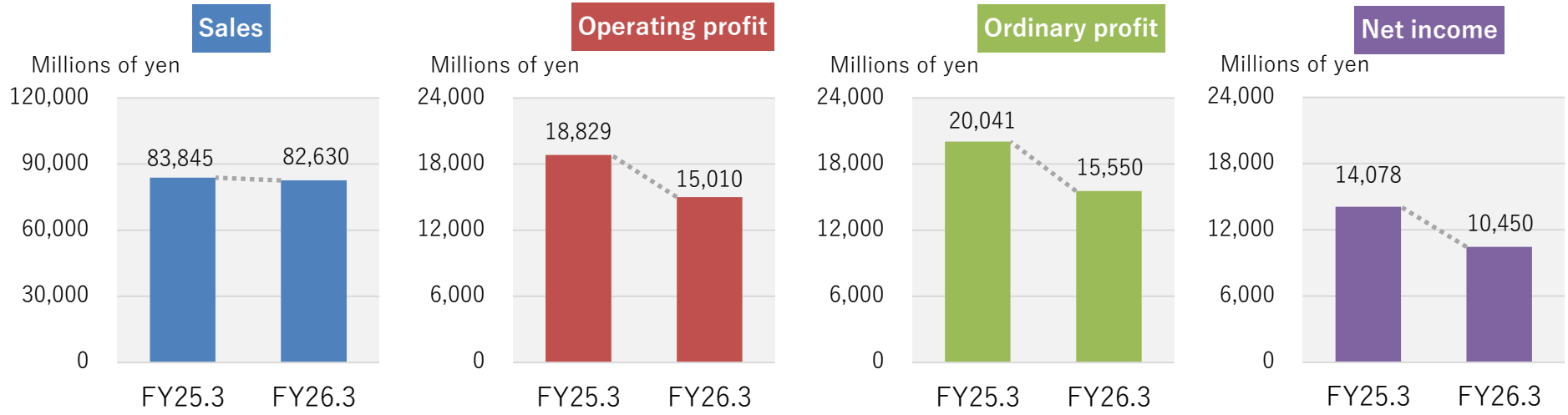
# Chemical Sales by Region

## FY3/25 Results

*Intersegment sales are included.



# FY3/26 Consolidated Forecast




| Millions of yen | FY3/25 Results | FY3/26 Forecast | Change | Percentage change |
|---|---|---|---|---|
| Sales | 83,845 | 82,630 | △ 1,215 | △ 1.4% |
| Operating profit | 18,829 | 15,010 | △ 3,819 | △ 20.3% |
| Ordinary profit | 20,041 | 15,550 | △ 4,491 | △ 22.4% |
| Net income | 14,078 | 10,450 | △ 3,628 | △ 25.8% |
| Exchange rate: $US | 151.69 yen | 141.02 yen | △ 10.67 yen | |

# FY3/26 Consolidated Forecasts

## ● Sales & Operating profit by Business Segment

| Millions of yen | Sales | | | | Operating profit | | | |
|---|---|---|---|---|---|---|---|---|
| | FY3/25 Results | FY3/26 Forecast | Change | Percentage change | FY3/25 Results | FY3/26 Forecast | Change | Percentage change |
| Surface Finishing Materials | 69,581 | 67,919 | △ 1,661 | △ 2.4% | 17,805 | 15,137 | △ 2,668 | △ 15.0% |
| Surface Finishing Machinery | 9,157 | 9,677 | + 520 | + 5.7% | 582 | 382 | △ 200 | △ 34.4% |
| Plating Job | 4,250 | 4,190 | △ 60 | △ 1.4% | △ 47 | △ 84 | △ 36 | - |
| Real Estate Rental | 832 | 820 | △ 12 | △ 1.5% | 467 | △ 448 | △ 915 | - |

## ● Sales by Chemicals Categories

| Millions of yen | FY3/25 Results | FY3/26 Forecast | Change | Percentage change |
|---|---|---|---|---|
| Chemicals for HDD | 2,624 | 2,880 | +255 | +9.7% |
| Chemicals for Wafer & PKG | 39,848 | 39,212 | △ 636 | △ 1.6% |
| Conventional Electroless Nickel | 4,317 | 4,234 | △ 83 | △ 1.9% |
| Others | 3,614 | 3,543 | △ 71 | △ 2.0% |
| Total | 50,405 | 49,869 | △ 536 | △ 1.1% |

### <Reference> Foreign exchange sensitivity

**Assumed rate for fiscal year ending March 31, 2026: 141.02 yen (JPY/USD)**

**Impact on full-year results:**

**If the yen depreciates by 1 yen**
- **Sales: increase by approx. ¥340 million**
- **Operating profit: increase by approx. ¥70 million**

**If the yen appreciates by 1 yen**
- **Sales: decrease by approx. ¥340 million**
- **Operating profit: decrease by approx. ¥70 million**

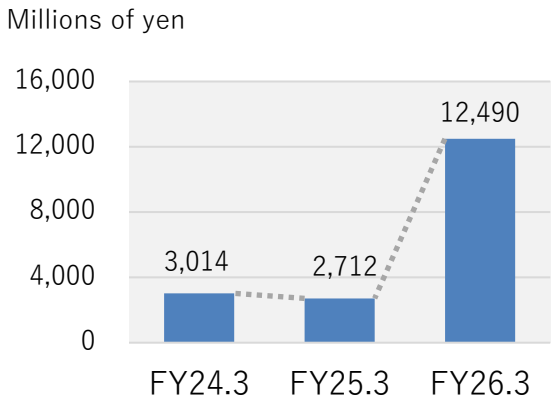
*It is assumed that other currencies move in tandem with the US dollar.

# Exchange Rates

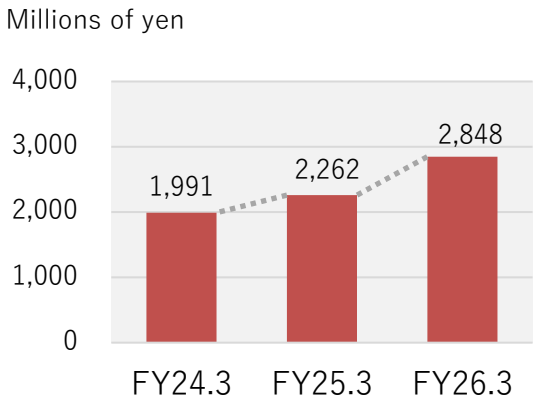


# Capital Expenditure, Depreciation and R&D Expenses

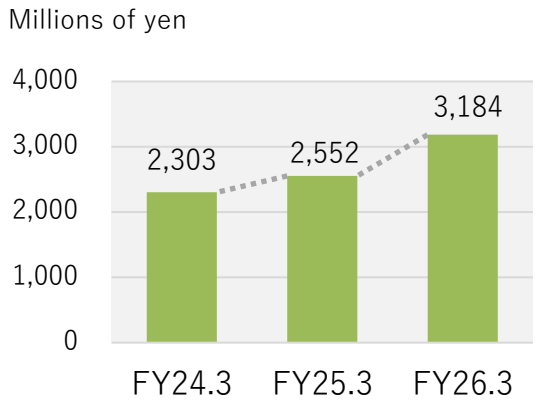
**Capital Expenditure**




**Depreciation**




**R&D Expenses**




| Millions of yen | FY3/24 Results | FY3/25 Results | FY3/26 Forecast |
|---|---|---|---|
| Capital Expenditure | 3,014 | 2,712 | 12,490 |
| Depreciation | 1,991 | 2,262 | 2,848 |
| R&D Expenses | 2,303 | 2,552 | 3,184 |

# Topic: Progress of the Hirakata Plant Reconstruction

## Plan to newly construct the Research Building No. 3 at the Central Research Laboratory

As part of the reconstruction of the Hirakata Plant, we plan to demolish the administration building in the Hirakata Plant and construct a new building (Research Building No. 3) at the Central Research Laboratory.

The functions of the administration building will be relocated to the welfare building in the same factory.

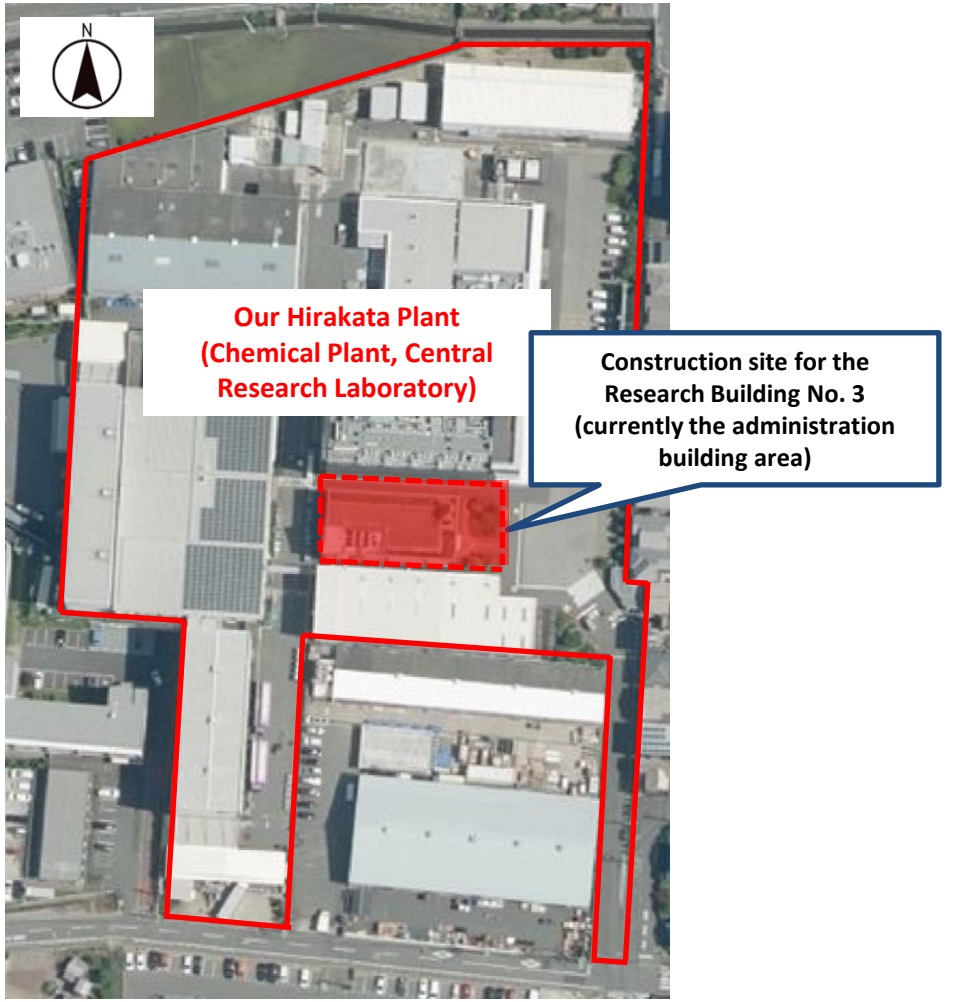
With the construction of the Research Building No. 3, we will strengthen our research and development capabilities and enhance our technical customer support system.

**Project outline of the Research Building No. 3 at the Central Research Laboratory**

- Location: 5-1, Deguchi 1-chome, Hirakata, Osaka (Hirakata Plant premises)
- Steel frame construction / Three stories above the ground (including the clean room)
- Building area: Approx. 1,800 $m^2$
- Planned investment: Approx. 2.0 billion yen (including demolition costs for the administration building)
- Scheduled for completion: March 2027

**Other plans for the Hirakata Plant reconstruction**

- New construction of a chemical plant (scheduled for completion: December 2027)
- Refurbishment of the existing chemical plant
- Remodeling of the product warehouses




An aerial photo taken by the Geospatial Information Authority of Japan, modified by Uyemura

# Topic: Renaming of Thai Subsidiary and Establishment of a Technical Center

## Change of Thai subsidiary name

Our Thai consolidated subsidiary, Sum Hitechs Co., Ltd., has changed its name to **Uyemura (Thailand) Co., Ltd.**, effective May 1, 2025, to enhance its brand recognition and expand its business in Thailand.

Going forward, we will promote the Uyemura brand and aim to further expand sales of the plating chemicals.

SUM → UYEMURA Thailand

## Establishment of a Thai technical center

To provide technical support to our customers in Thailand, we will establish a dedicated laboratory on the site of the former plating processing line and promote the expansion of sales of the plating chemicals.

**Project outline of the Thai technical center**

- Location: Navanakorn Industrial Estate Zone, Pathumthani, Thailand (in the existing plant premises)
- Planned investment: Approx. 28 million yen
- Scheduled for completion: June 2025


Uyemura (Thailand) Co., Ltd.

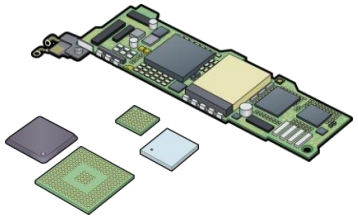
# Business Environment

# Basic Strategy for Sales

**We aim for higher customer satisfaction**
**We are committed to action with sincerity**

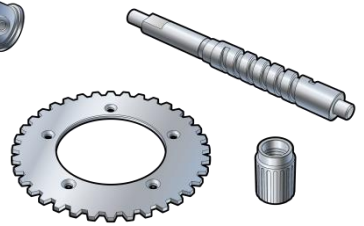
- **Sales and development strategies that accelerate the growth of our share in markets where it is already high**
- **Sales and development strategies that increase our share in markets where it is still low**
- **Manufacturing strategy aligned with market trend**
- **Provision of total solutions including chemicals, machines and control systems**

# Basic Strategy for Sales









Capability of analyzing all kinds of plating chemicals


Wafer plating equipment for power devices

# Business Environment

- **Current market condition**

1. Domestic market: Moderate growth in PC-related, telecommunication, and power devices.
   Strong demand for hard disks. Server-related products are on a gradual recovery trend, although it varies depending on the target field of end users.

2. Overseas market: Almost similar trend as the domestic market

**Technologies we are currently focusing on**

Next-generation package technology, substrate technology for telecommunication, car electronics technology, and environment-related technologies

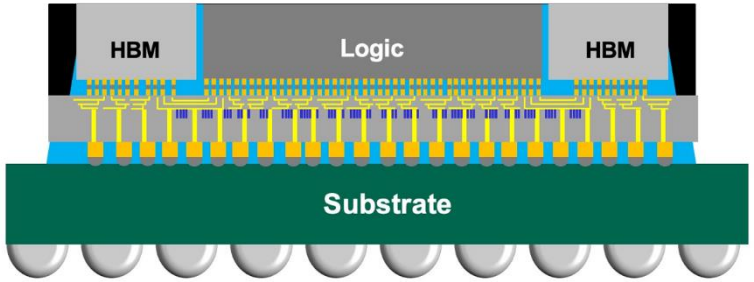
- **Technologies we should focus on going forward**

Wiring technology and bump bonding technology for advanced package

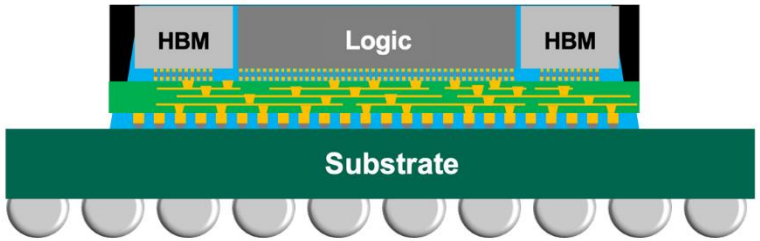
Surface finishing technology for next-generation bonding materials and environment-friendly total technology development

# Technology Required for Advanced Package

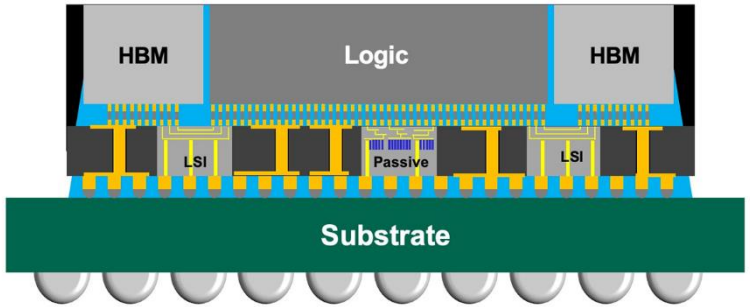
Silicon interposer type

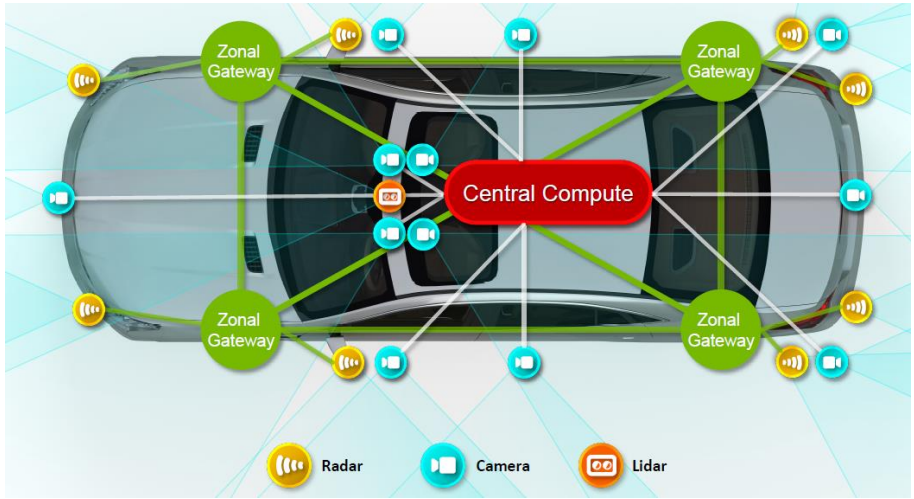



Organic interposer type




Silicon bridge type



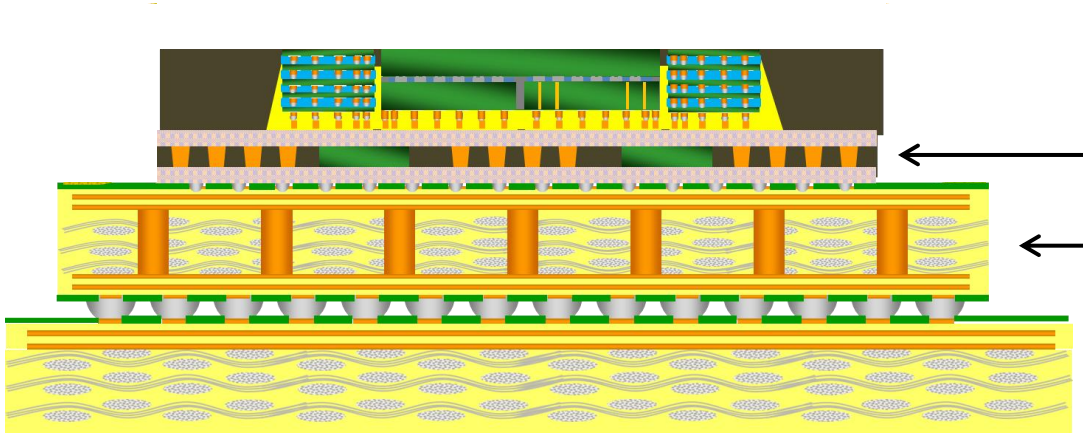

https://3dfabric.tsmc.com/japanese/dedicatedFoundry/technology/cowos.htm

1) Adaptation to high-reliability base materials
2) Making progress in high-reliability bonding technology
3) Taking on a challenge of environmentally friendly technology

Sailing into the future of the semiconductor industry, TSMC, IEDM2024-technology innovations shaping the roadmap

# Possibility of Glass-core Application to Advanced Package

Package substrate

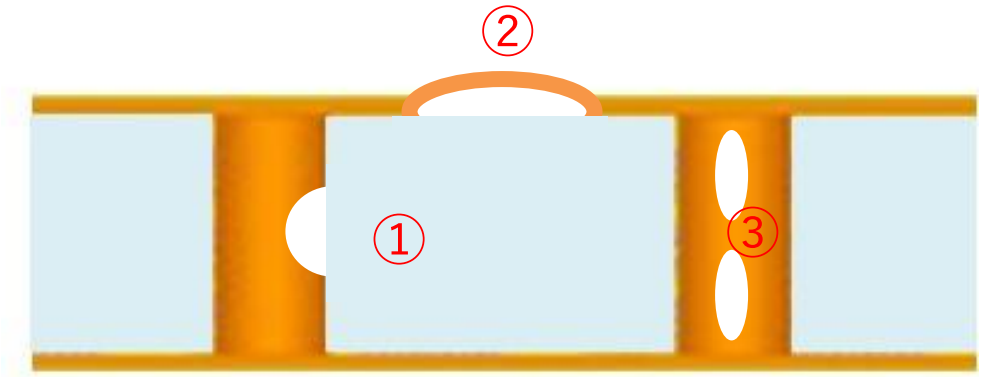


Interposer

Substrate

| Glass characteristics | Demand characteristics |
|---|---|
| ■ High rigidity | → Torsion dimensional accuracy |
| ■ Low thermal expansion coefficient | → Warpage dimensional accuracy |
| ■ High smoothness | → Fine wiring formation |

Glass adoption for interposers and substrates toward fine wiring




Glass substrate with a through hole

Concerns

① Disconnection in a through hole

② Wiring adhesion

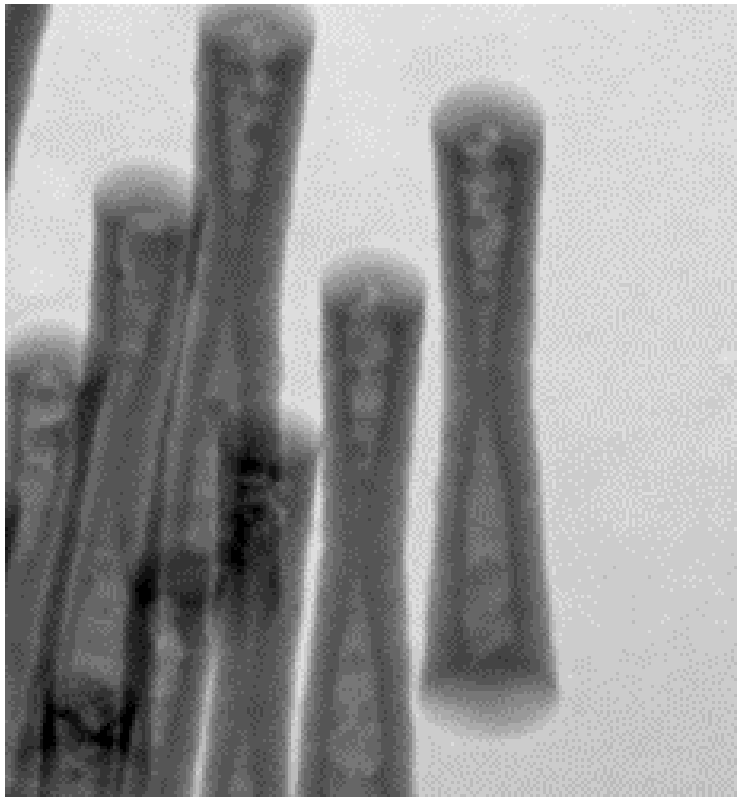
③ Embeddability inside through holes

# Proposal of Seed Layer for Glass Core and TH Filling Electrolytic Cu

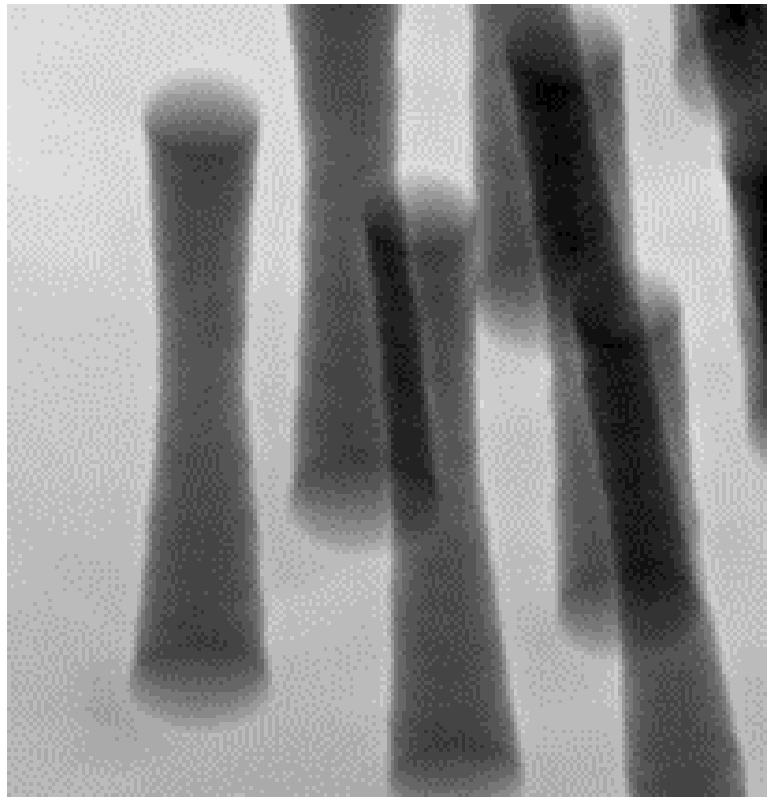
MOSL
(Metal Oxide Seed Layer)

Electroless Cu
(Seed for Electrolytic Cu)

Electrolytic Cu
(TH Filling)



Old electrolytic Cu

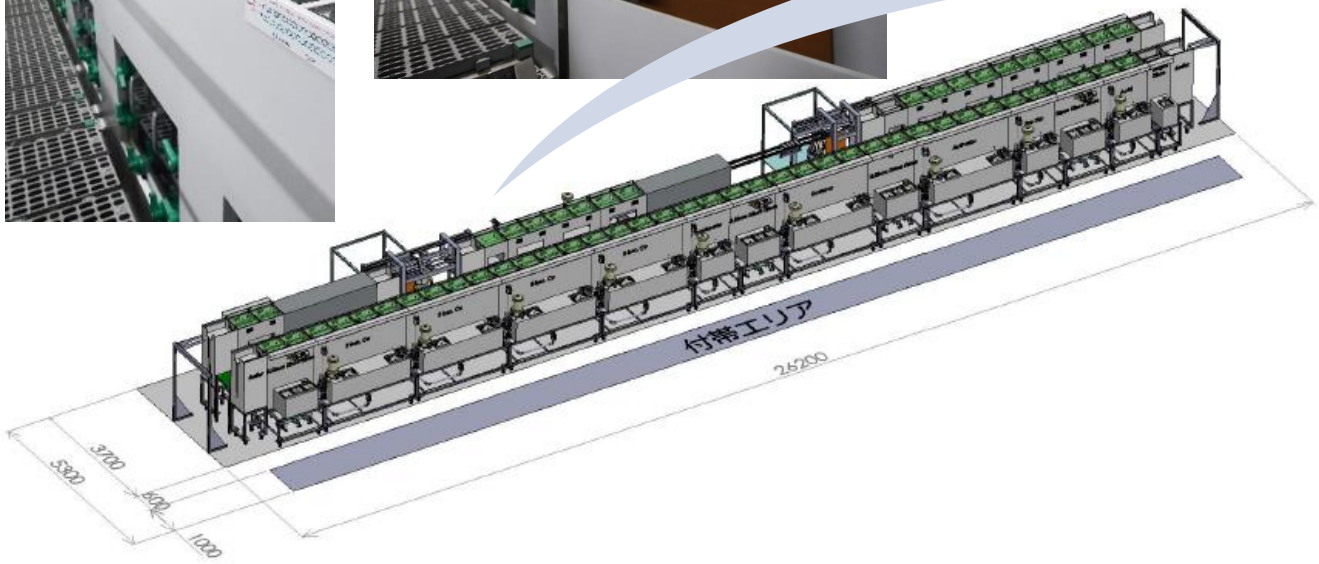


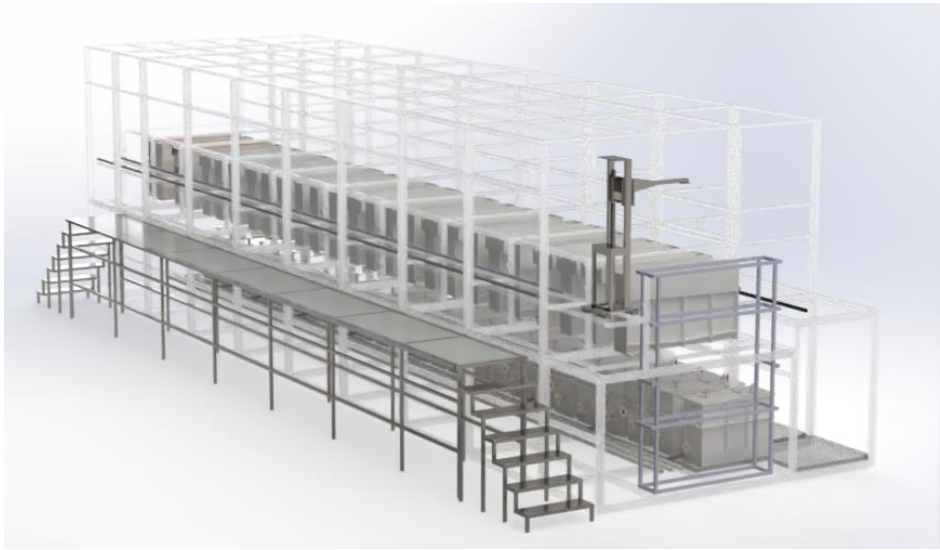
New electrolytic Cu

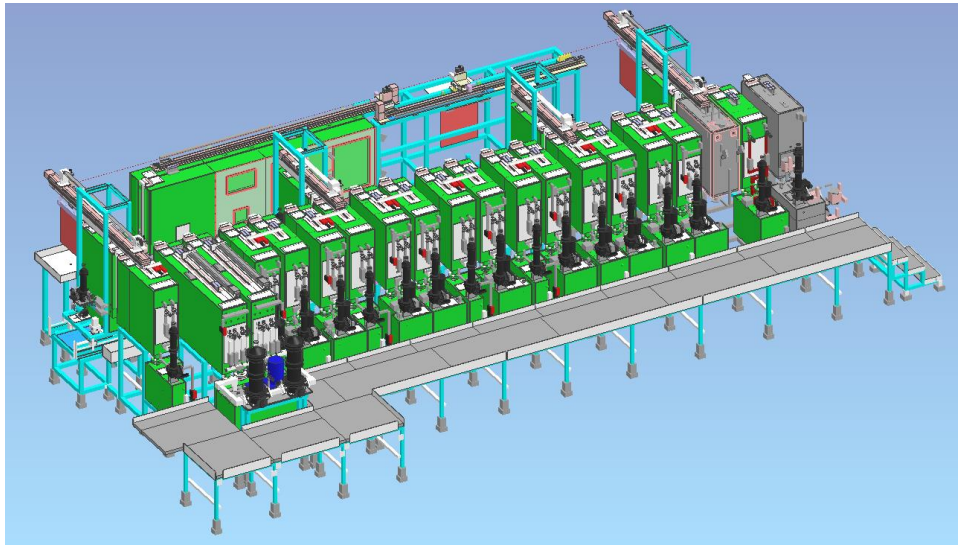
| | |
|---|---|
| TGV opening diameter | 100 μm |
| TGV center diameter | 70 μm |
| Board thickness | 600 μm |

# Evolution of Uemura's Vertical Continuous Plating System (U-VCPS )

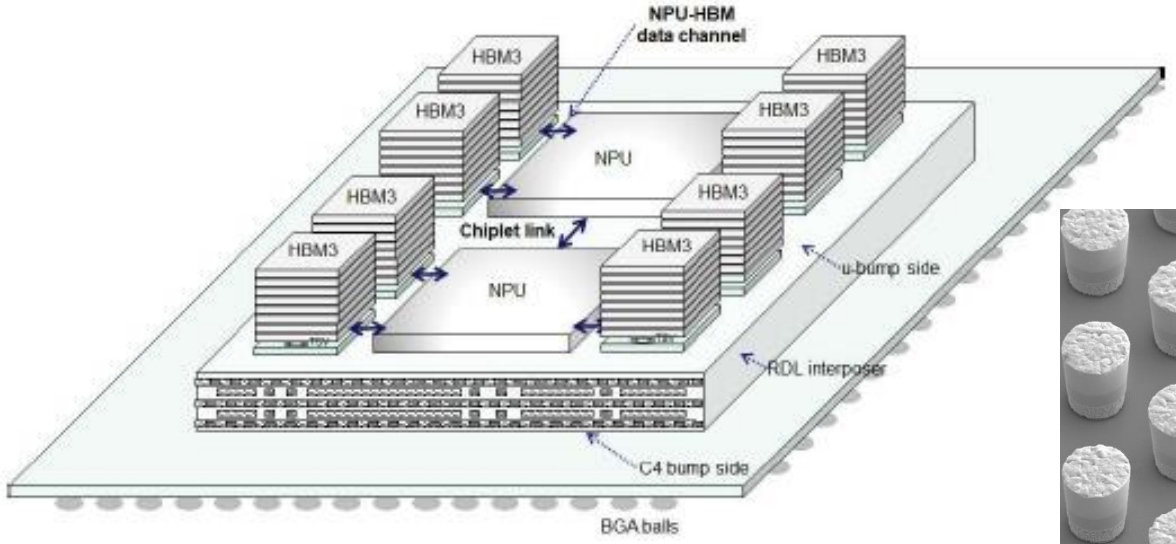
Applicability to thin organic substrate less than 50um, including coreless substrate, and glass substrate



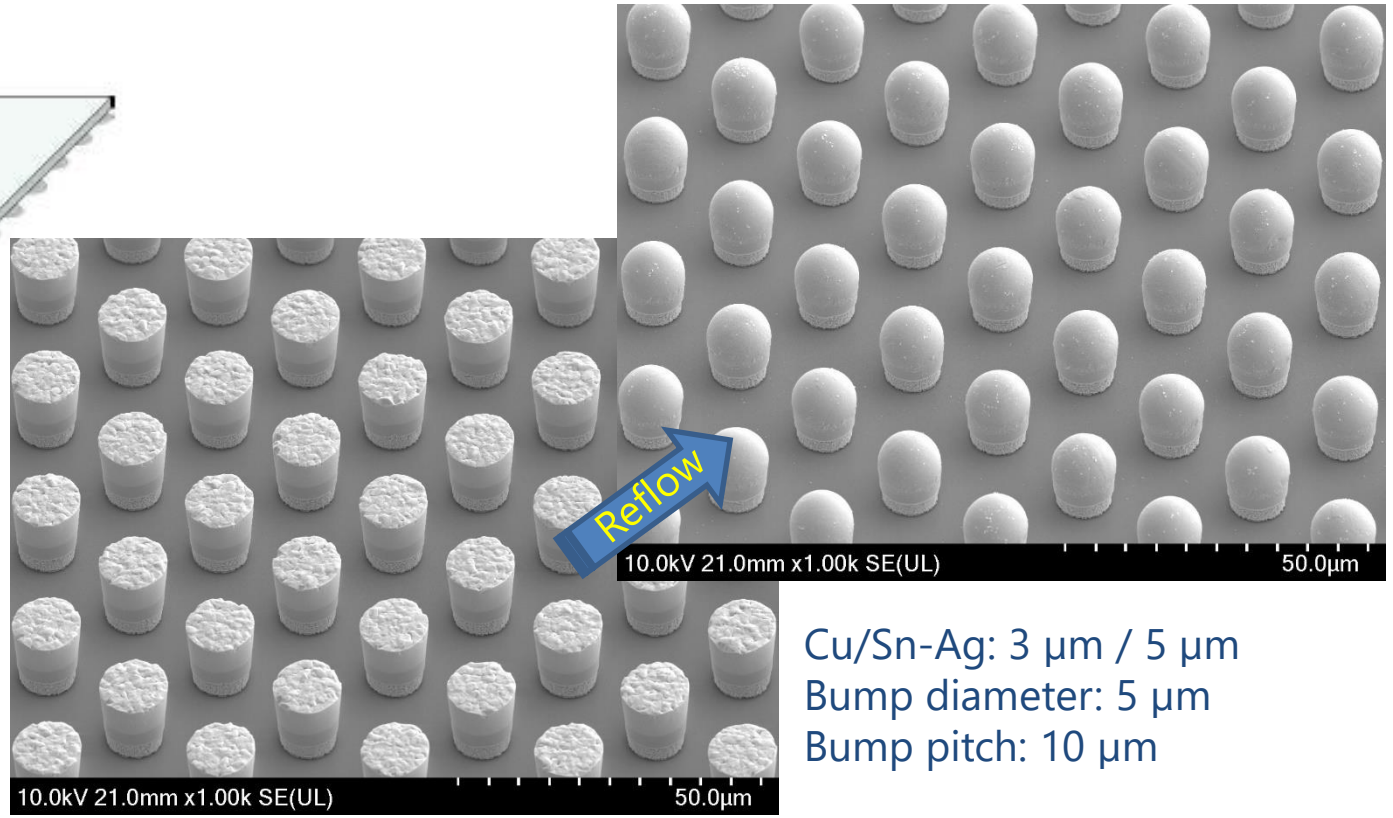





# Proposal of Bump Formation Technology for Advanced Package




Chiplet Heterogeneous-Integration AI Processor, International conference on Electronics, Information and Communication (ICEIC), February 2023

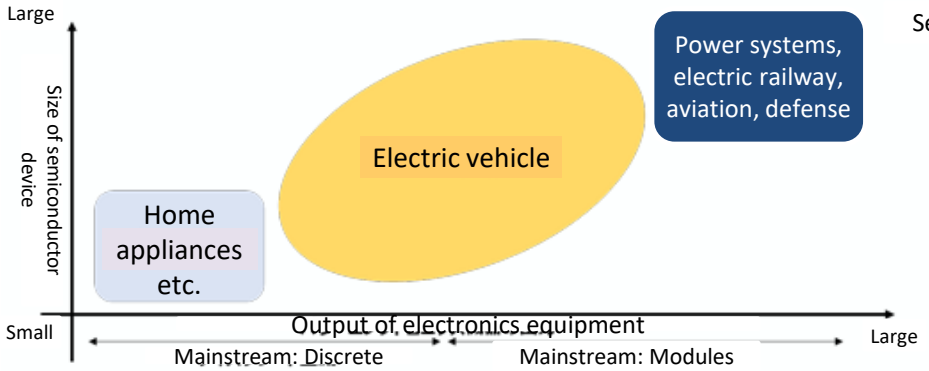



Cu/Sn-Ag: 3 µm / 5 µm
Bump diameter: 5 µm
Bump pitch: 10 µm

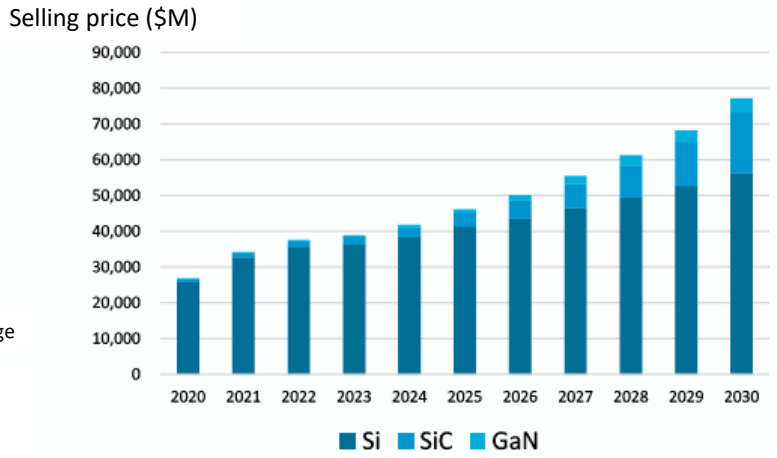
New Energy and Industrial Technology Development Organization (NEDO) Research and Development Project of the Enhanced Infrastructures for Post-5G Information and Communication Systems (JPNP20017)

# Technology Required for Next-generation Power Semiconductors

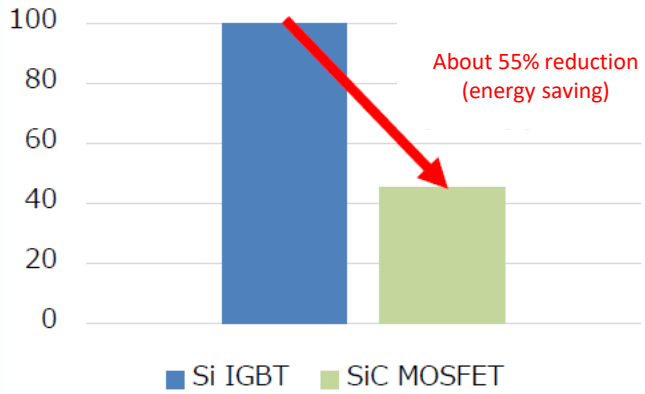
Features and applications of power semiconductors




Demand forecast for power semiconductors




Energy loss of Si / SiC power semiconductors




* Assumed application is inverters for rail vehicles
* Vertical axis (energy loss) is 100 for Si power semiconductors

Source: Current Status and Future of Semiconductor and Digital Industry Strategy, published by METI on December 23, 2024

**SiC features**

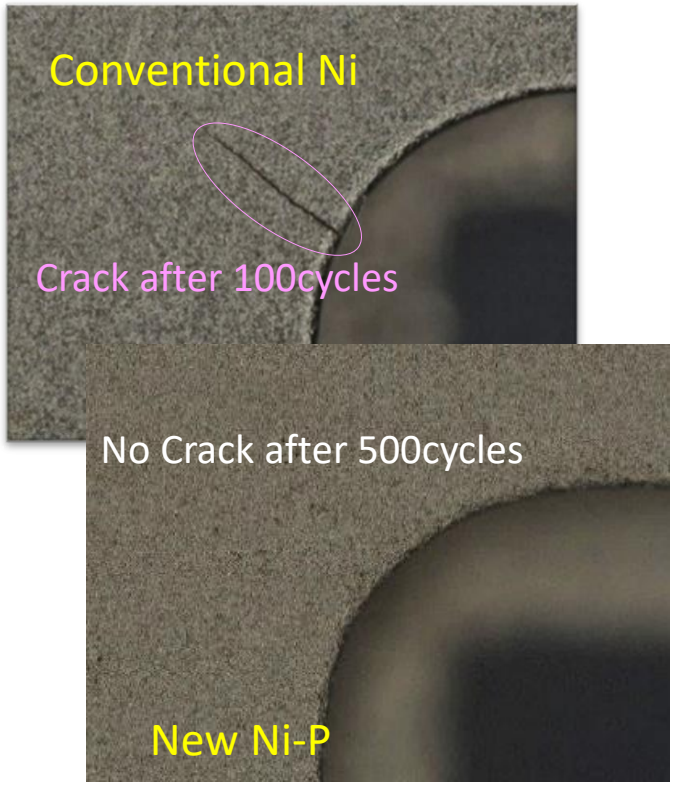
1) Power loss reduction
2) High operating temperature
3) High speed switching motion
4) High heat dissipation effect

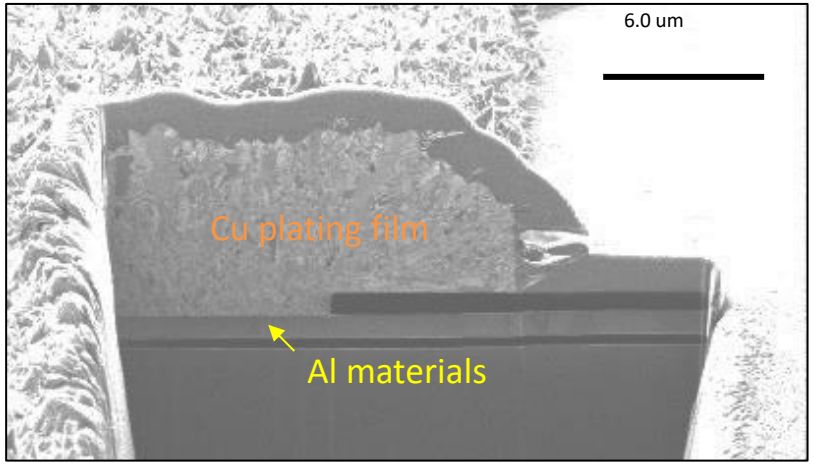
Materials for high operating temperature
→ Sintering materials, encapsulation materials, surface finishing, etc.

# Proposal for the Development of Processes Appropriate for New Bonding Materials (Ag sintering, Cu sintering and Cu wires)

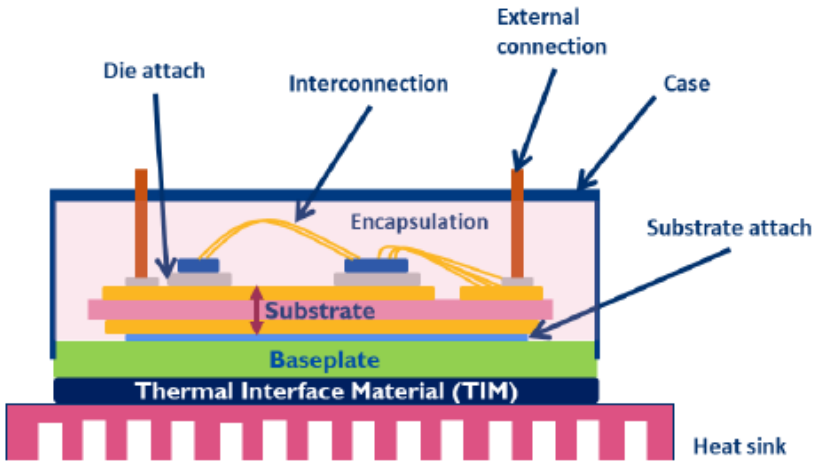
Ni-P film formation with excellent heat-crack resistance

After TCT(-50℃⇔250℃)

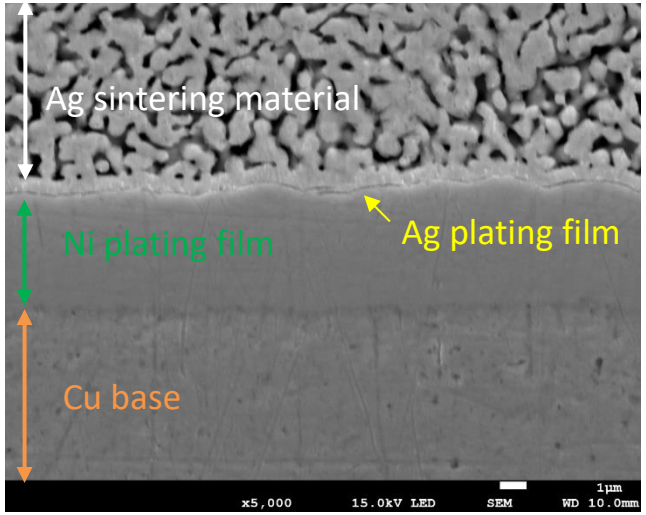



Direct electroless Cu plating on Al with excellent bondability for sintered Cu and Cu wires




Ag film formation with excellent bondability for Ag sintering materials




Status of the Power Module Packaging Industry 2021-Market and Technology Report, Yole development, November 2021

# ESG and SDG Related Initiatives

Under the Uyemura Group slogan of “Growing together with (:You),” our aims are to grow and prosper together with our stakeholders and to be a company that is able to contribute to society.

## Environment

Development and expansion of sales of environmentally friendly products and technologies

Development and delivery of products that will lead to the development of society and improvement of the environment

Reduction of waste and water consumption

Use of clean energy and reduction of electricity consumption

**Realization of a sustainable society**

## Social

Promotion of social and community contribution activities

Automation of factory process from order receipt to shipment

Development of workplace environments where employees can work energetically

## Governance

Thorough compliance with laws and regulations and respect for human rights

Implementation of business continuity plan

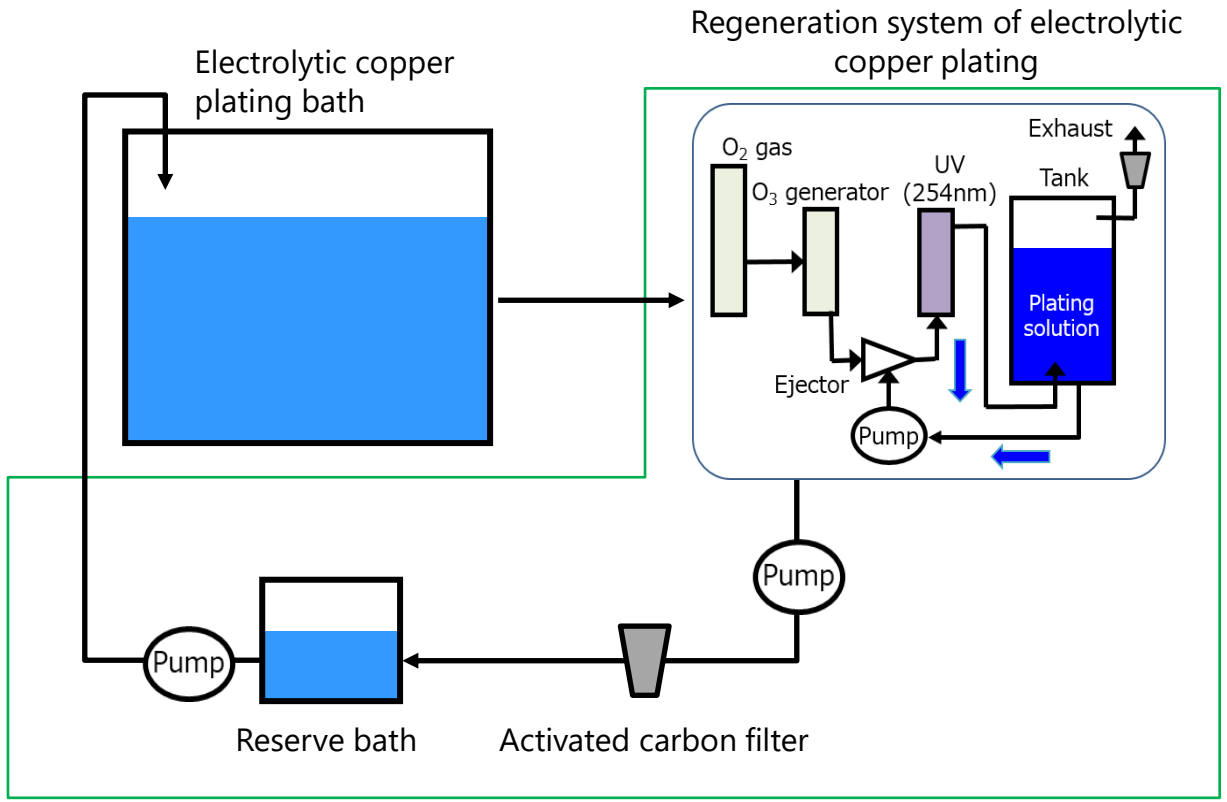
**Please refer to our website for detailed information on our initiatives.**

# Environmentally Friendly Products: Proactive approach to SDGs

1. Pb-free plating bath
   - Electroless Ni plating bath mainly for general bathes.
   - Pb-free electro Sn plating bath, such as pure Sn and Sn-Ag bath for electronic parts
2. Cyan-free bath
   - Electroless Au plating bath with no supply of cyanide-free and fee cyanide for wafers and electronic parts.
3. Desmear-free process
   - Process without the use of dangerous permanganate for substrates
4. Formalin-free bath and process without the use of formalin
   - Development of formalin-free electroless Cu bath for wafers
5. PFOS-free bath and PFOA-free bath
   - PTFE composite plating mainly for automobile parts
6. Wastewater treatment
   - Plating solution recycle unit
7. $CO_2$ reduction
   - Low-melting-point bonding material plating and final surface finishing suitable for low-melting-point bonding

# Proposal for the Reduction in Wastewater through a Regeneration System of Electrolytic Copper Plating Bath

## Illustrative image of electrolytic copper plating regeneration system




## Conventional

Electrolytic copper plating solution is totally waste after a certain period of use due to waste accumulation

## New proposal

Overall performance of plating solution is constant with a regeneration system that decomposes a part of plating solution and removes waste

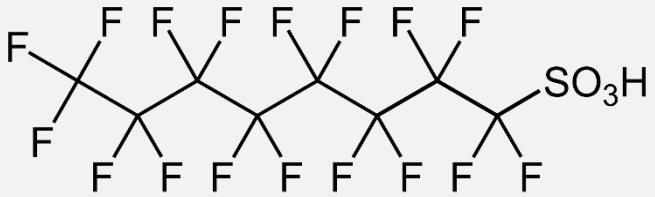
→ Semi-permanent plating solution life

# Proposals for Achieving Compliance with Environmental Regulations for PTFE Co-deposition Plating Bath

REACH (Registration, Evaluation, Authorization and Restrictions of Chemicals)

PFAS : Per- and PolyFluoroAlkyl Substances

PFOS : perfluorooctanesulfonic acid




**2011~ PFOS free type**

NIMUFLON, NIMUFLON FUL (Type B)

**2019~ PFOA free type**

NIMUFLON, NIMUFLON FUL (Type JB)

PFOA : perfluorooctanoic acid


**2024~ PFAS free type**

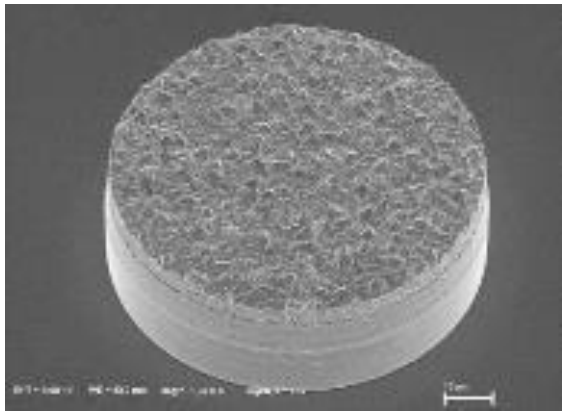
NIMUFLON FUL (FPR-1) (Development completed)

Ongoing development to accommodate various PTFE co-deposition amounts.

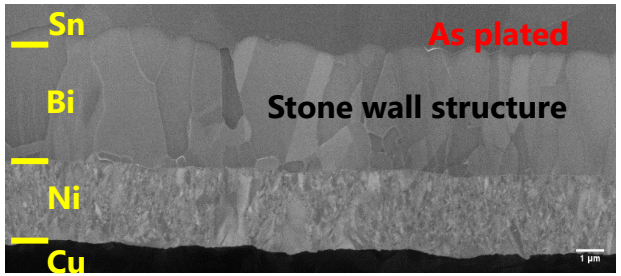
# Proposal of Low-melting-point Solder Bonding Technology to Reduce $CO_2$

Low-melting point → Power saving → $CO_2$ reduction

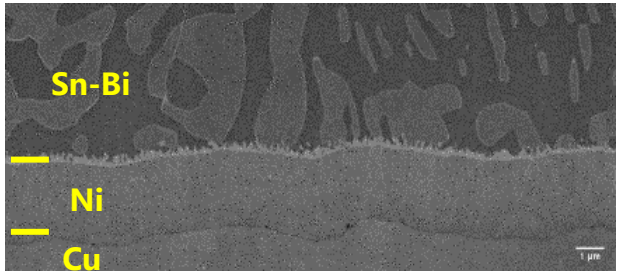
1) Bump plating for low-melting- point solder materials



Sn **surface**
(Cu/Ni/Bi/Sn)

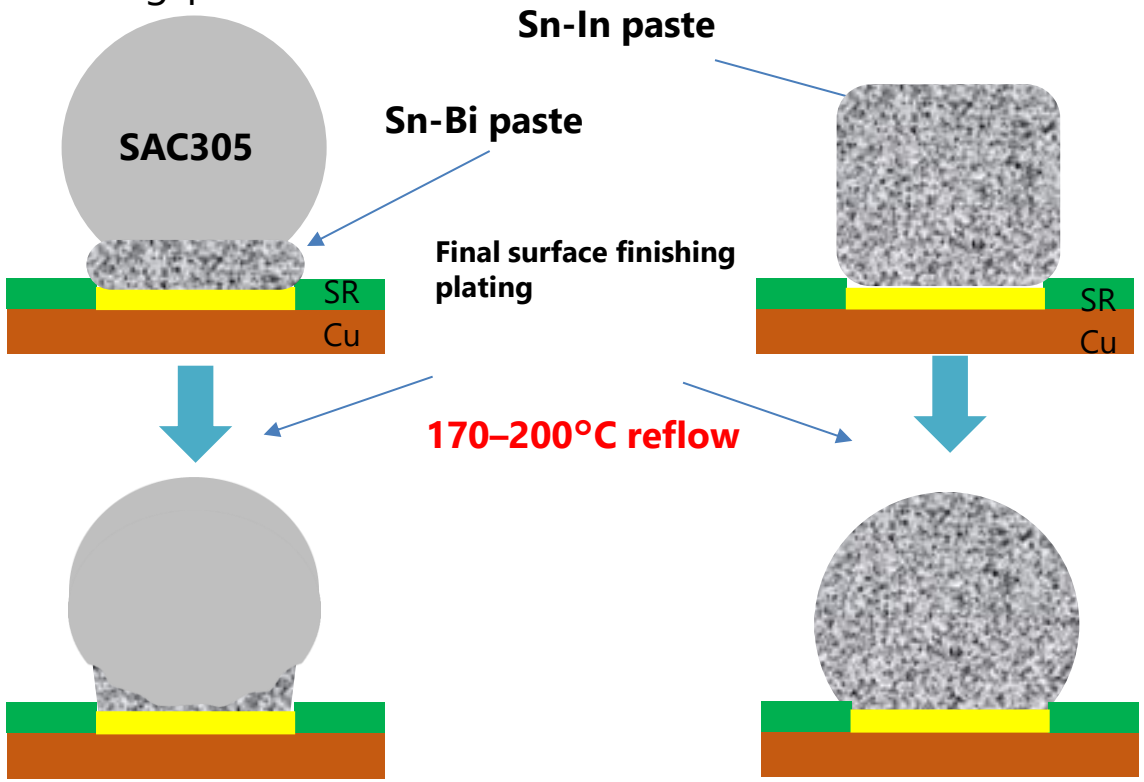



150°C reflow




Solder/solder joint for low temperature reflow by multi plating method, Wafer-level Packaging Symposium, January 2023

2) Examination of final surface finishing suitable for low-melting-point solder materials



# Uyemura Group Companies

| Company name | Foundation | Location | Business |
|---|---|---|---|
| C.Uyemura & Co., Ltd. | 1848 (Establishment) 1933 (Incorporated) | Japan | |
| Uyemura International Corporation | 1985 | US | |
| Uyemura International (Hong Kong) Co., Ltd. | 1986 | China (Hong Kong) | |
| Taiwan Uyemura Co., Ltd. | 1987 | Taiwan | |
| Uyemura (Thailand) Co., Ltd. | 1987 | Thailand | |
| Uyemura (Shenzhen) Co., Ltd. | 1988 | China (Shenzhen) | |
| Uyemura International (Singapore) Pte Ltd | 1992 | Singapore | |
| Uyemura (Malaysia) Sdn. Bhd. | 1996 | Malaysia | |
| Uyemura (Shanghai) Co., Ltd. | 2002 | China (Shanghai) | |
| Uyemura Korea Co., Ltd. | 2010 | Korea | |
| PT.Uyemura Indonesia | 2012 | Indonesia | |

Sales R&D Chemical Production Machinery Production Plating Job Real Estate Rental

Forecasts of future performance in this report are based on assumptions judged to be valid and information currently available to the Company, but are not promises by the Company regarding future performance. Actual results are affected by various factors and may differ substantially.

# Growing together with

## Uyemura Group Companies

| | | | |
|---|---|---|---|
| • Japan | C.Uyemura & Co., Ltd. | • Taiwan | Taiwan Uyemura Co., Ltd. |
| • USA | Uyemura International Corporation | • Korea | Uyemura Korea Co., Ltd. |
| • Hong Kong | Uyemura International (Hong Kong) Co., Ltd. | • Singapore | Uyemura International (Singapore) Pte Ltd |
| • Shenzhen | Uyemura (Shenzhen) Co., Ltd. | • Malaysia | Uyemura (Malaysia) Sdn. Bhd. |
| • Shanghai | Uyemura (Shanghai) Co., Ltd. | • Thailand | Uyemura Thailand Co., Ltd. |
| | | • Indonesia | PT. Uyemura Indonesia |